

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









# Le58QL02/021/031

## Quad Low Voltage Subscriber Line Audio-Processing Circuit VE580 Series

### **APPLICATIONS**

■ Codec function on telephone switch line cards

#### **FEATURES**

- Low-power, 3.3 V CMOS technology with 5-V tolerant digital inputs
- Software and coefficient compatible to the Le79Q02/ 021/031 QSLAC™ device
- Performs the functions of four codec/filters
- Software programmable:
  - SLIC device input impedance
  - Transhybrid balance
  - Transmit and receive gains
  - Equalization (frequency response)
  - Digital I/O pins
  - Programmable debouncing on one input
  - Time slot assigner
  - Programmable clock slot and PCM transmit clock edge options
- Standard microprocessor interface
- A-law, μ-law, or linear coding
- Single or Dual PCM ports available
  - Up to 128 channels (PCLK at 8.192 MHz) per PCM port
  - Optional supervision on the PCM highway
- 1.536, 1.544, 2.048, 3.072, 3.088, 4.096, 6.144, 6.176, or
   8.192 MHz master clock derived from MCLK or PCLK
- Built-in test modes with loopback, tone generation, and μP access to PCM data
- Mixed state (analog and digital) impedance scaling
- Performance guaranteed over a 12 dB gain range
- Real Time Data register with interrupt (open drain or TTL output)
- Supports multiplexed SLIC device outputs
- Broadcast state
- 256 kHz or 293 kHz chopper clock for Legerity SLIC devices with switching regulator
- Maximum channel bandwidth for V.90 modems

#### RELATED LITERATURE

- 080754 Le58QL061/063 QLSLAC<sup>™</sup> Device Data Sheet
- 080761 QSLAC<sup>™</sup> to QLSLAC<sup>™</sup> Device Design Conversion Guide
- 080758 QSLAC<sup>™</sup> to QLSLAC<sup>™</sup> Guide to New Designs

### ORDERING INFORMATION

Device	Package (Green) <sup>1</sup>	Packing <sup>2</sup>
Le58QL02FJC	44-pin PLCC	Tube
Le58QL021FJC	44-pin PLCC	Tube
Le58QL021BVC	44-pin TQFP	Tray
Le58QL031DJC	32-pin PLCC	Tube

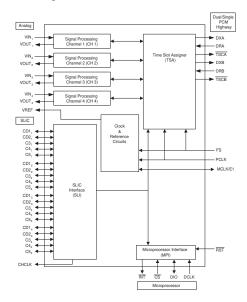
- The green package meets RoHS Directive 2002/95/EC of the European Council to minimize the environmental impact of electrical equipment.
- 2. For delivery using a tape and reel packing system, add a "T" suffix to the OPN (Ordering Part Number) when placing an order.

### **DESCRIPTION**

The Le58QL02/021/031 Quad Low Voltage Subscriber Line Audio-Processing Circuit (QLSLAC™) devices integrate the key functions of analog line cards into high-performance, very-programmable, four-channel codec-filter devices. The QLSLAC devices are based on the proven design of Legerity's reliable SLAC™ device families. The advanced architecture of the QLSLAC devices implements four independent channels and employs digital filters to allow software control of transmission, thus providing a cost-effective solution for the audio-processing function of programmable line cards. The QLSLAC devices are software and coefficient compatible to the QSLAC devices.

Advanced submicron CMOS technology makes the Le58QL02/021/031 QLSLAC devices economical, with both the functionality and the low power consumption needed in line card designs to maximize line card density at minimum cost. When used with four Legerity SLIC devices, a QLSLAC device provides a complete software-configurable solution to the BORSCHT functions.

#### **BLOCK DIAGRAM**



Document ID# **080753** Date: **April 09, 2009** Version: **9** 

Distribution: Public Document

## **TABLE OF CONTENTS**

APPLICATIONS1
FEATURES1
ORDERING INFORMATION1
RELATED LITERATURE
DESCRIPTION
BLOCK DIAGRAM
TABLE OF CONTENTS
LIST OF FIGURES
LIST OF TABLES
PRODUCT DESCRIPTION
BLOCK DESCRIPTIONS
Clock and Reference Circuits
Microprocessor Interface (MPI)
Time Slot Assigner (TSA)
Signal Processing Channels (CHx)
SLIC Device Interface (SLI)
CONNECTION DIAGRAMS
PIN DESCRIPTIONS10
ABSOLUTE MAXIMUM RATINGS12
OPERATING RANGES12
Environmental Ranges
Electrical Ranges12
ELECTRICAL CHARACTERISTICS
Transmission Characteristics
Group Delay Distortion
Gain Linearity
Total Distortion Including Quantizing Distortion18
Discrimination Against Out-of-Band Input Signals
Discrimination Against 12- and 16-kHz Metering Signals
Overload Compression
SWITCHING CHARACTERISTICS
SWITCHING WAVEFORMS
OPERATING THE QLSLAC DEVICE
Power-Up Sequence
Channel Enable (EC) Register
SLIC Device Control and Data Lines
Clock Mode Operation
E1 Multiplex Operation
Real-Time Data Register Operation
Interrupt
Interrupt Mask Register
Active State
Inactive State
Reset States
SIGNAL PROCESSING

Overview of Digital Filters	33
Two-Wire Impedance Matching	
Frequency Response Correction and Equalization	33
Transhybrid Balancing	
Gain Adjustment	
Transmit Signal Processing	
Transmit PCM Interface	
Receive Signal Processing	
Receive PCM Interface	
Analog Impedance Scaling Network (AISN)	
Speech Coding	
Signaling on the PCM Highway	
Robbed-Bit Signaling Compatibility	
Default Filter Coefficients	
COMMAND DESCRIPTION AND FORMATS	
Command Field Summary	
Microprocessor Interface Description	
·	
SUMMARY OF MPI COMMANDS	40
MPI COMMAND STRUCTURE	40
00h Deactivate (Standby State)	41
02h Software Reset	
04h Hardware Reset	
06h No Operation	
0Eh Activate Channel (Operational State)	
40/41h Write/Read Transmit Time Slot and PCM Highway Selection	
42/43h Write/Read Receive Time Slot and PCM Highway Selection	
44/45h Write/Read Transmit Clock Slot, Receive Clock Slot, and Transmit Clock Edg	
· · · · · · · · · · · · · · · · · · ·	
46/4/n Write/Read Chip Configuration Register	43
46/47h Write/Read Chip Configuration Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register	44
4A/4Bh Write/Read Channel Enable and Operating Mode Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register.  4D/4Fh Read Real-Time Data Register.  50/51h Write/Read AISN and Analog Gains.  52/53h Write/Read SLIC Device Input/Output Register.  54/55h Write/Read SLIC Input/Output Direction, Read Status Bits.  60/61h Write/Read Operating Functions.  6C/6Dh Write/Read Interrupt Mask Register.  70/71h Write/Read Operating Conditions.	
4A/4Bh Write/Read Channel Enable and Operating Mode Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register.  4D/4Fh Read Real-Time Data Register.  50/51h Write/Read AISN and Analog Gains.  52/53h Write/Read SLIC Device Input/Output Register.  54/55h Write/Read SLIC Input/Output Direction, Read Status Bits.  60/61h Write/Read Operating Functions.  6C/6Dh Write/Read Interrupt Mask Register.  70/71h Write/Read Operating Conditions.  73h Read Revision Code Number (RCN)	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients	
4A/4Bh Write/Read Channel Enable and Operating Mode Register  4D/4Fh Read Real-Time Data Register  50/51h Write/Read AISN and Analog Gains  52/53h Write/Read SLIC Device Input/Output Register  54/55h Write/Read SLIC Input/Output Direction, Read Status Bits  60/61h Write/Read Operating Functions  6C/6Dh Write/Read Interrupt Mask Register  70/71h Write/Read Operating Conditions  73h Read Revision Code Number (RCN)  80/81h Write/Read GX Filter Coefficients	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR)	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients 88/89h Write/Read R Filter Coefficients	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients 88/89h Write/Read R Filter Coefficients 96/97h Write/Read B2 Filter Coefficients (IIR)	
4A/4Bh Write/Read Channel Enable and Operating Mode Register.  4D/4Fh Read Real-Time Data Register.  50/51h Write/Read AISN and Analog Gains.  52/53h Write/Read SLIC Device Input/Output Register.  54/55h Write/Read SLIC Input/Output Direction, Read Status Bits.  60/61h Write/Read Operating Functions.  6C/6Dh Write/Read Interrupt Mask Register.  70/71h Write/Read Operating Conditions.  73h Read Revision Code Number (RCN).  80/81h Write/Read GX Filter Coefficients.  82/83h Write/Read GR Filter Coefficients (FIR and IIR).  86/87h Write/Read B1 Filter Coefficients.  88/89h Write/Read X Filter Coefficients.  88/89h Write/Read R Filter Coefficients.  96/97h Write/Read B2 Filter Coefficients (IIR).  98/99h Write/Read FIR Z Filter Coefficients (FIR only).	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read R Filter Coefficients 96/97h Write/Read B2 Filter Coefficients (IIR) 98/99h Write/Read FIR Z Filter Coefficients (FIR only) 9A/9Bh Write/Read IIR Z Filter Coefficients (IIR only)	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients 96/97h Write/Read B2 Filter Coefficients (IIR) 98/99h Write/Read FIR Z Filter Coefficients (FIR only) 9A/9Bh Write/Read IIR Z Filter Coefficients (IIR only) C8/C9h Write/Read Debounce Time Register	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read R Filter Coefficients 96/97h Write/Read R Filter Coefficients (IIR) 98/99h Write/Read B2 Filter Coefficients (FIR only) 9A/9Bh Write/Read IIR Z Filter Coefficients (IIR only) C8/C9h Write/Read Debounce Time Register CDh Read Transmit PCM Data E8/E9h Write/Read Ground Key Filter	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients 96/97h Write/Read R Filter Coefficients (IIR) 98/99h Write/Read FIR Z Filter Coefficients (FIR only) 9A/9Bh Write/Read IIR Z Filter Coefficients (IIR only) C8/C9h Write/Read Debounce Time Register CDh Read Transmit PCM Data E8/E9h Write/Read Ground Key Filter	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients 88/89h Write/Read R Filter Coefficients 96/97h Write/Read B2 Filter Coefficients (IIR) 98/99h Write/Read FIR Z Filter Coefficients (FIR only) 9A/9Bh Write/Read IIR Z Filter Coefficients (IIR) C8/C9h Write/Read Debounce Time Register CDh Read Transmit PCM Data E8/E9h Write/Read Ground Key Filter  PROGRAMMABLE FILTERS General Description of CSD Coefficients	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients 88/89h Write/Read R Filter Coefficients 96/97h Write/Read B2 Filter Coefficients (IIR) 98/99h Write/Read FIR Z Filter Coefficients (FIR only) 9A/9Bh Write/Read IIR Z Filter Coefficients (IIR only) C8/C9h Write/Read Debounce Time Register CDh Read Transmit PCM Data E8/E9h Write/Read Ground Key Filter  PROGRAMMABLE FILTERS General Description of CSD Coefficients User Test States and Operating Conditions	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register. 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register. 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits. 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register. 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN). 80/81h Write/Read GX Filter Coefficients. 82/83h Write/Read GR Filter Coefficients (FIR and IIR). 86/87h Write/Read B1 Filter Coefficients. 88/89h Write/Read X Filter Coefficients. 88/89h Write/Read X Filter Coefficients. 88/89h Write/Read R Filter Coefficients. 96/97h Write/Read B2 Filter Coefficients (IIR). 98/99h Write/Read B1 Z Filter Coefficients (IIR). 98/99h Write/Read B1 Z Filter Coefficients (IIR). 98/99h Write/Read Debounce Time Register. CDh Read Transmit PCM Data. E8/E9h Write/Read Ground Key Filter.  PROGRAMMABLE FILTERS. General Description of CSD Coefficients. User Test States and Operating Conditions A-Law and μ-Law Companding.	
4A/4Bh Write/Read Channel Enable and Operating Mode Register. 4D/4Fh Read Real-Time Data Register. 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register. 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN) 80/81h Write/Read GX Filter Coefficients 82/83h Write/Read GR Filter Coefficients 84/85h Write/Read Z Filter Coefficients (FIR and IIR) 86/87h Write/Read B1 Filter Coefficients 88/89h Write/Read X Filter Coefficients 8A/8Bh Write/Read R Filter Coefficients 96/97h Write/Read B2 Filter Coefficients (IIR) 98/99h Write/Read B1 Filter Coefficients (FIR only) 9A/9Bh Write/Read Debounce Time Register CDh Read Transmit PCM Data E8/E9h Write/Read Ground Key Filter  PROGRAMMABLE FILTERS General Description of CSD Coefficients User Test States and Operating Conditions A-Law and μ-Law Companding  APPLICATIONS	
4A/4Bh Write/Read Channel Enable and Operating Mode Register 4D/4Fh Read Real-Time Data Register. 50/51h Write/Read AISN and Analog Gains 52/53h Write/Read SLIC Device Input/Output Register. 54/55h Write/Read SLIC Input/Output Direction, Read Status Bits. 60/61h Write/Read Operating Functions 6C/6Dh Write/Read Interrupt Mask Register. 70/71h Write/Read Operating Conditions 73h Read Revision Code Number (RCN). 80/81h Write/Read GX Filter Coefficients. 82/83h Write/Read GR Filter Coefficients (FIR and IIR). 86/87h Write/Read B1 Filter Coefficients. 88/89h Write/Read X Filter Coefficients. 88/89h Write/Read X Filter Coefficients. 88/89h Write/Read R Filter Coefficients. 96/97h Write/Read B2 Filter Coefficients (IIR). 98/99h Write/Read B1 Z Filter Coefficients (IIR). 98/99h Write/Read B1 Z Filter Coefficients (IIR). 98/99h Write/Read Debounce Time Register. CDh Read Transmit PCM Data. E8/E9h Write/Read Ground Key Filter.  PROGRAMMABLE FILTERS. General Description of CSD Coefficients. User Test States and Operating Conditions A-Law and μ-Law Companding.	

APPLICATION CIRCUIT	61
LINE CARD PARTS LIST	61
PHYSICAL DIMENSIONS	62
32-Pin PLCC	62
44-Pin PLCC	
44-Pin TQFP	34
REVISION HISTORY	<b>6</b> 5
Revision A1 to A2	35
Revision A2 to B1	35
Revision B1 to C1	
Revision C1 to D1	
Revision D1 to E1	
Revision E1 to F1	
Revision F1 to F2	35
Revision F2 to Version 9	35

## **LIST OF FIGURES**

Figure 1.	Le58QL02JC 44-Pin PLCC	.7
Figure 2.	Le58QL021JC 44-Pin PLCC	.8
Figure 3.	Le58QL031JC 32-Pin PLCC	.8
Figure 4.	Le58QL021VC 44-Pin PLCC	.9
Figure 5.	Transmit Path Attenuation vs. Frequency	15
Figure 6.	Receive Path Attenuation vs. Frequency	15
Figure 7.	Group Delay Distortion	16
Figure 8.	A-law Gain Linearity with Tone Input (Both Paths)	17
Figure 9.	μ-law Gain Linearity with Tone Input (Both Paths)	17
Figure 10.	Total Distortion with Tone Input (Both Paths)	18
Figure 11.	Discrimination Against Out-of-Band Signals	19
Figure 12.	Spurious Out-of-Band Signals	
Figure 13.	Analog-to-Analog Overload Compression	21
Figure 14.	Input and Output Waveforms for AC Tests	24
Figure 15.	Microprocessor Interface (Input Mode)	
Figure 16.	Microprocessor Interface (Output Mode)	
Figure 17.	PCM Highway Timing for XE = 0 (Transmit on Negative PCLK Edge)	
Figure 18.	PCM Highway Timing for XE = 1 (Transmit on Positive PCLK Edge)	
Figure 19.	Master Clock Timing	
Figure 20.	Clock Mode Options	
Figure 21.	SLIC Device I/O E1 Multiplex and Real-Time Data Register Operation	
Figure 22.	E1 Multiplex Internal Timing	
Figure 23.	MPI Real-Time Data Register	
Figure 24.	QLSLAC Device Transmission Block Diagram	
Figure 25.	Robbed-Bit Frame	
Figure 26.	Le7920 SLIC/QLSLAC Device Application Circuit	31
LIST OF	TABLES	
	QLSLAC Device Configurations	
Table 2.	0 dBm0 Voltage Definitions with Unity Gain in X, R, GX, GR, AX, and AR	14
Table 3.	Channel Parameters	38
	Channel Monitors	
	Global Chip Parameters	
	Global Chip Status Monitors	
	A-Law: Positive Input Values	
Table 8.	μ-Law: Positive Input Values	59

### PRODUCT DESCRIPTION

The QLSLAC device performs the codec/filter and two-to-four-wire conversion functions required of the subscriber line interface circuitry in telecommunications equipment. These functions involve converting audio signals into digital PCM samples and converting digital PCM samples back into audio signals. During conversion, digital filters are used to band limit the voice signals. All of the digital filtering is performed in digital signal processors operating from a master clock, which can be derived either from PCLK or MCLK.

Four independent channels allow the QLSLAC device to function as four SLAC<sup>TM</sup> devices. For programming information, each channel has its own enable bit (EC1, EC2, EC3, and EC4) to allow individual channel programming. If more than one Channel Enable bit is High or if all Channel Enable bits are High, all channels enabled will receive the programming information written; therefore, a Broadcast mode can be implemented by simply enabling all channels in the device to receive the information. The Channel Enable bits are contained in the Channel Enable (EC) register, which is written and read using Command 4A/4Bh. The Broadcast mode is useful in initializing QLSLAC devices in a large system.

The user-programmable filters set the receive and transmit gain, perform the transhybrid balancing function, permit adjustment of the two-wire termination impedance, and provide equalization of the receive and transmit paths. All programmable digital filter coefficients can be calculated using the WinSLAC™ software.

Data transmitted or received on the PCM highway can be 8-bit companded code (with an optional 8-bit signaling byte in the transmit direction) or 16-bit linear code. The 8-bit codes appear 1 byte per time slot, while the 16-bit code appears in two consecutive time slots. The compressed PCM codes can be either 8-bit companded A-law or  $\mu$ -law. The PCM data is read from and written to the PCM highway in user-programmable time slots at rates of 128 kHz to 8.192 MHz. The transmit clock edge and clock slot can be selected for compatibility with other devices that can be connected to the PCM highway.

Three configurations of the QLSLAC device are offered with single or dual PCM highways. The Le58QL02 and Le58QL021 QLSLAC devices with dual and single PCM highways respectively are available in the 44-pin packages. The Le58QL031JC QLSLAC device is a single PCM highway version in a 32-pin PLCC package.

	· ·			
PCM Highway	Programmable I/O per Channel	Chopper Clock	Package	Part Number
Dual	Four I/O	Yes	44 PLCC	Le58QL02JC
Single	Five I/O	No	44 PLCC/TQFP	Le58QL021JC (or VC)
Single	Two I/O	No	32 PLCC	Le58QL031JC

Table 1. QLSLAC Device Configurations

### **BLOCK DESCRIPTIONS**

#### **Clock and Reference Circuits**

This block generates a master clock and a frame sync signal for the digital circuits. It also generates an analog reference voltage for the analog circuits.

### **Microprocessor Interface (MPI)**

This block communicates with the external control microprocessor over a serial interface. It passes user control information to the other blocks, and it passes status information from the blocks to the user. In addition, this block contains the reset circuitry.

### **Time Slot Assigner (TSA)**

This block communicates with the PCM highway, where the PCM highway is a time division mutiplexed bus carrying the digitized voice samples. The block implements programmable time slots and clocking arrangements in order to achieve a first layer of switching. Internally, this block communicates with the Signal Processing Channels (CHx).

## Signal Processing Channels (CHx)

These blocks do the transmission processing for the voice channels. Part of the processing is analog and is interfaced to the VIN and VOUT pins. The remainder of the processing is digital and is interfaced to the Time Slot Assigner (TSA) block.

## **SLIC Device Interface (SLI)**

This block communicates digitally with the SLIC device circuits. It sends control bits to the SLIC devices to control modes and to operate LEDs and optocouplers. It also accepts supervision information from the SLIC devices and performs some filtering.

### **CONNECTION DIAGRAMS**

Figure 1. Le58QL02JC 44-Pin PLCC

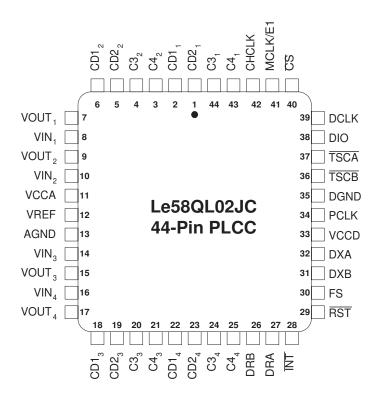


Figure 2. Le58QL021JC 44-Pin PLCC

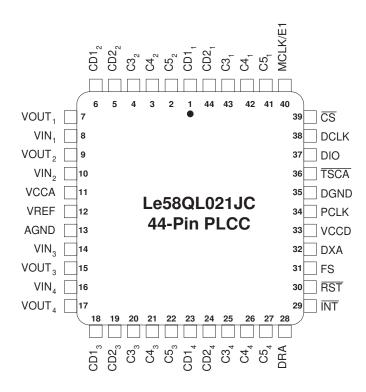


Figure 3. Le58QL031JC 32-Pin PLCC

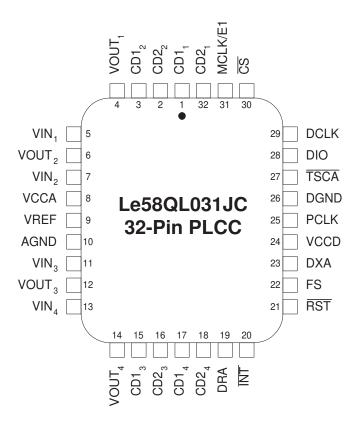
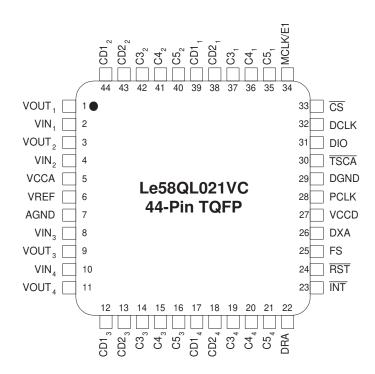


Figure 4. Le58QL021VC 44-Pin PLCC



## **PIN DESCRIPTIONS**

Pin Names	Туре	Description
AGND, DGND	Power	Separate analog and digital grounds are provided to allow noise isolation; however, the two grounds are connected inside the part, and the grounds must also be connected together on the circuit board.
CD1 <sub>1</sub> –CD1 <sub>4</sub> , CD2 <sub>1</sub> –CD2 <sub>4</sub>	Inputs/Outputs	Control and Data. CD1 and CD2 are TTL compatible programmable Input or Output (I/O) ports. They can be used to monitor or control the state of the SLIC drivce or any other device associated with the subscriber line interface. The direction, input or output, is programmed using MPI Command 54/55h. As outputs, CD1 and CD2 can be used to control relays, illuminate LEDs, or perform any other function requiring a latched TTL compatible signal for control. The output state of CD1 and CD2 is written using MPI Command 52h. As inputs, CD1 and CD2 can be processed by the QLSLAC device (if programmed to do so). CD1 can be debounced before it is made available to the system. The debounce time is programmable from 0 to 15 ms in 1 ms increments using MPI Command C8/C9h. CD2 can be filtered using the up/down counter facility and programming the sampling interval using MPI Command E8/E9h.  Additionally, CD1 can be demultiplexed into two separate inputs using the E1 demultiplexing function. The E1 demultiplexing function of the QLSLAC device was designed to interface directly to Legerity SLIC devices supporting the ground key function. With the proper Legerity SLIC device and the E1 function of the QLSLAC device enabled, the CD1 bit can be demultiplexed into an Off-Hook/Ring Trip signal and Ground Key signal. In the demultiplex mode, the second bit, Ground Key, takes the place of the CD2 as an input. The demultiplexed bits can be debounced (CD1) or filtered (CD2) as explained previously. A more complete description of CD1, CD2, debouncing, and filtering functions is contained in Operating the OLSLAC Device, on page 27.  Once the CD1 and CD2 inputs are processed (Debounced, Filtered and/or Demultiplexed) by the QLSLAC device, the information can be accessed by the system in two ways: 1) on a per channel basis along with C3, C4, and C5 of the specific channel using MPI Command 53h, or 2) by using MPI Command 4D/4Fh, which obtain the CD1 and CD2 bits from all four channels simultaneously. This feature reduces the processor overhea
C3 <sub>1</sub> –C3 <sub>4</sub> , C4 <sub>1</sub> –C4 <sub>4</sub> , C5 <sub>1</sub> –C5 <sub>4</sub>	Inputs/Outputs	Control. C3, C4, and C5 are TTL-compatible programmable Input or Output (I/O) ports. They can be used to monitor or control the state of the SLIC device or any other device associated with subscriber line interface. The direction, input or output, is programmed using MPI Command 54/55h. As outputs, C3, C4, and C5 can be used to control relays, illuminate LEDs, or perform any other function requiring a latched TTL compatible signal for control. The output state of C3, C4, and C5 is written using MPI Command 52h. As inputs, C3, C4, and C5 can be accessed by the system by using MPI Command 53h.  The Le58QL021 QLSLAC device contains a single PCM highway and five programmable I/Os per channel (CD1, CD2, C3, C4, and C5) in a 44-pin PLCC or TQFP package. In the Le58QL02 QLSLAC device, the C5 <sub>1</sub> , C5 <sub>2</sub> , C5 <sub>3</sub> , and C5 <sub>4</sub> I/Os are eliminated, enabling dual PCM highways and a chopper clock output in a 44-pin PLCC or TQFP package. In the Le58QL031 QLSLAC device, the C3 <sub>1</sub> –C5 <sub>1</sub> , C3 <sub>2</sub> –C5 <sub>2</sub> , C3 <sub>3</sub> –C5 <sub>3</sub> , and C3 <sub>4</sub> –C5 <sub>4</sub> I/Os are eliminated, enabling a single PCM highway and two control and data I/Os (CD1, CD2) per channel in a 32-pin PLCC package.
CHCLK	Output	Chopper Clock. This output provides a 256 kHz or a 292.57 kHz, 50% duty cycle, TTL-compatible clock for use by up to four SLIC devices with built-in switching regulators. The CHCLK frequency is synchronous to the master clock, but the phase relationship to the master clock is random. The chopper clock is not available in all package types.
<del>CS</del>	Input	Chip Select. The Chip Select input (active Low) enables the device so that control data can be written to or read from the part. The channels selected for the write or read operation are enabled by writing 1 s to the appropriate bits in the Channel Enable Register of the QLSLAC device prior to the command. See EC1, EC2, EC3, and EC4 of the Command <u>4A/4Bh Write/Read Channel Enable and Operating Mode Register</u> , on page <u>44</u> for more information. If Chip Select is held Low for 16 rising edges of DCLK, a hardware reset is executed when Chip Select returns High.
DCLK	Input	Data Clock. The Data Clock input shifts data into and out of the microprocessor interface of the QLSLAC device. The maximum clock rate is 8.192 MHz.
DIO	Input/Output	Data. Control data is serially written into and read out of the QLSLAC device via the DIO pin, with the most significant bit first. The Data Clock determines the data rate. DIO is high impedance except when data is being transmitted from the QLSLAC device.

Pin Names	Туре	Description
DRA, DRB	Inputs	PCM Data Receive A/B. The PCM data for channels 1, 2, 3, and 4 is serially received on either the DRA or DRB port during user-programmed time slots. Data is always received with the most significant bit first. For compressed signals, 1 byte of data for each channel is received every 125 $\mu s$ at the PCLK rate. In the Linear state, two consecutive bytes of data for each channel are received every 125 $\mu s$ at the PCLK rate. DRB is not available on all package types.
DXA, DXB	Outputs	PCM Data Transmit. The transmit data from channels 1, 2, 3, and 4 is sent serially out on either the DXA or DXB port or both ports during user-programmed time slots. Data is always transmitted with the most significant bit first. The output is available every 125 $\mu s$ and the data is shifted out in 8-bit (16-bit in Linear or PCM Signaling state) bursts at the PCLK rate. DXA and DXB are High impedance between time slots, while the device is in the Inactive state with no PCM signaling, or while the Cutoff Transmit Path bit (CTP) is on. DXB is not available on all package types.
FS	Input	Frame Sync. The Frame Sync pulse is an 8 kHz signal that identifies Time Slot 0, Clock Slot 0 of a system's PCM frame. The QLSLAC device references individual time slots with respect to this input, which must be synchronized to PCLK.
ĪNT	Output	Interrupt. INT is an active Low output signal which is programmable as either TTL compatible or open drain. The INT output goes Low any time one of the input bits in the Real Time Data register changes state and is not masked. It also goes Low any time new transmit data appears if this interrupt is armed. INT remains Low until the appropriate register is read via the microprocessor interface, or the QLSLAC device receives either a software or hardware reset. The individual CD <sub>xy</sub> bits in the Real Time Data register can be masked from causing an interrupt by using MPI Command 6C/6Dh. The transmit data interrupt must be armed with a bit in the Operating Conditions register.
MCLK/E1	Input/Output	Master Clock (Input)/Enable CD1 Multiplex (Output). The Master Clock can be a 1.536 MHz, 1.544 MHz, or 2.048 MHz (times 1, 2, or 4) clock for use by the digital signal processor. If the internal clock is derived from the PCM Clock Input (PCLK), this pin can be used as an E1 output to control Legerity SLIC devices having multiplexed hookswitch and ground-key detector outputs.
PCLK	Input	PCM Clock. The PCM clock determines the rate at which PCM data is serially shifted into or out of the PCM ports. PCLK is an integer multiple of the frame sync frequency. The maximum clock frequency is 8.192 MHz and the minimum clock frequency is 128 kHz for dual PCM highway versions and 256 kHz for single PCM highway versions. The minimum clock rate must be doubled if Linear state or PCM signaling is used. PCLK frequencies between 1.03 MHz and 1.53 MHz are not allowed. Optionally, the digital signal processor clock can be derived from PCLK rather than MCLK.
RST	Input	Reset. A logic Low signal at this pin resets the QLSLAC device to its default state. The RST pin may be tied to VCCD if it is not needed in the system.
TSCA, TSCB	Outputs	Time Slot Control. The Time Slot Control outputs are open drain <u>outputs</u> ( <u>requiring</u> pull-up resistors to VCCD) and are normally inactive (High impedance). TSCA or TSCB is active (Low) when PCM data is transmitted on the DXA or DXB pin respectively.
VCCA, VCCD	Power	Analog and digital power supply inputs. VCCA and VCCD are provided to allow for noise isolation and proper power supply decoupling techniques. For best performance, all of the VCC power supply pins should be connected together at the connector of the printed circuit board.
VIN <sub>1</sub> -VIN <sub>4</sub>	Inputs	Analog Input. The analog voice band signal is applied to the VIN input of the QLSLAC device. The VIN input is biased at VREF by a large internal resistor. The audio signal is sampled, digitally processed and encoded, and then made available at the TTL-compatible PCM output (DXA or DXB). If the digitizer saturates in the positive or negative direction, VIN is pulled by a reduced resistance toward AGND or VCCD, respectively. VIN <sub>1</sub> is the input for channel 1, VIN <sub>2</sub> is the input for channel 2, VIN <sub>3</sub> is the input for channel 3, and VIN <sub>4</sub> is the input for channel 4.
VOUT <sub>1</sub> - VOUT <sub>4</sub>	Outputs	Analog Output. The received digital data at DRA or DRB is processed and converted to an analog signal at the VOUT pin. VOUT <sub>1</sub> is the output from channel 1, VOUT <sub>2</sub> is the output for channel 2, VOUT <sub>3</sub> is the output from channel 3, and VOUT <sub>4</sub> is the output for channel 4. The VOUT voltages are referenced to VREF.
VREF	Output	Analog Voltage Reference. The VREF output is provided in order for an external capacitor to be connected from VREF to ground, filtering noise present on the internal voltage reference. VREF is buffered before it is used by internal circuitry. The voltage on VREF and the output resistance are given in <i>Electrical Characteristics</i> , on page 13. The leakage current in the capacitor must be low.

### **ABSOLUTE MAXIMUM RATINGS**

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Storage Temperature	−60° C < T <sub>A</sub> < +125° C
Ambient Temperature, under Bias	-40° C < T <sub>A</sub> < +85° C
Ambient relative humidity (non condensing)	5 to 95%
V <sub>CCA</sub> with respect to AGND	-0.4 to + 4.0 V
V <sub>CCA</sub> with respect to VCCD	±0.4 V
V <sub>CCD</sub> with respect to DGND	-0.4 to + 4.0 V
V <sub>IN</sub> with respect to AGND	-0.4 V to (V <sub>CCA</sub> + 0.4 V)
AGND with respect to DGND	±50 mV
Digital pins with respect to DGND	-0.4 to 5.5 V or VCCD + 2.37 V, whichever is smaller
Total combined CD1-C5 current per device:	
Source from VCCD	40 mA
Sink into DGND	40 mA
Latch up immunity (any pin)	± 100 mA
Total VCC current if rise rate of VCC > 0.4 V/μs	0.5 A

#### **Package Assembly**

The green package devices are assembled with enhanced environmental compatible lead (Pb), halogen, and antimony-free materials. The leads possess a matte-tin plating which is compatible with conventional board assembly processes or newer lead-free board assembly processes.

Refer to IPC/JEDEC J-Std-020 Table 4-2 for recommended peak soldering temperature and Table 5-2 for the recommended solder reflow temperature profile.

#### **OPERATING RANGES**

Legerity guarantees the performance of this device over commercial (0 to 70°C) and industrial (-40 to 85°C) temperature ranges by conducting electrical characterization over each range and by conducting a production test with single insertion coupled to periodic sampling. These characterization and test procedures comply with section 4.6.2 of Bellcore GR-357-CORE Component Reliability Assurance Requirements for Telecommunications Equipment.

### **Environmental Ranges**

Ambient Temperature	-40° C < T <sub>A</sub> < +85° C
Ambient Relative Humidity	15 to 85%

## **Electrical Ranges**

Analog Supply V <sub>CCA</sub>	+3.3 V ± 5%
Thinking cuppity V <sub>CCA</sub>	V <sub>CCD</sub> ± 50 mV
Digital Supply V <sub>CCD</sub>	+3.3 V ± 5%
DGND	0 V
AGND	±10 mV
CFIL Capacitance: VREF to AGND	0.1 μF ± 20%
Digital Pins	DGND to +5.25 V

## **ELECTRICAL CHARACTERISTICS**

Typical values are for  $TA = 25^{\circ}$  C and nominal supply voltages. Minimum and maximum values are over the temperature and supply voltage ranges shown in Operating Ranges, except where noted.

Symbol	Parameter Descriptions	Min	Тур	Max	Unit	Note
V <sub>IL</sub>	Digital Input Low voltage			0.8	V	
V <sub>IH</sub>	Digital Input High voltage	2.0			]	
	Digital Input leakage current					
$I_IL$	0 < V < VCCD	<b>-7</b>		+7	μΑ	
	Otherwise	-120		+180		
$V_{HYS}$	Digital Input hysteresis	0.16	0.25	0.34	V	
V <sub>OL</sub>	Digital Output Low voltage  CD1-C5 (I <sub>OL</sub> = 4 mA)  CD1-C5 (I <sub>OL</sub> = 8 mA)  TSCA, TSCB (I <sub>OL</sub> = 14 mA)  Other digital outputs (I <sub>OL</sub> = 2 mA)			0.4 0.8 0.4 0.4	V	1
V <sub>OH</sub>	Digital Output High voltage $CD1-C5$ ( $I_{OH}=4$ mA) $CD1-C5$ ( $I_{OH}=8$ mA) Other digital outputs ( $I_{OH}=400$ $\mu$ A)	V <sub>CCD</sub> - 0.4 V V <sub>CCD</sub> - 0.8 V 2.4			V	1
	Digital Output leakage current (H <sub>I</sub> Z state)					
$I_{OL}$	0 < V < VCCD	<b>-7</b>		+7	μΑ	
	Otherwise	-120		+180		
GIN	Input attenuator gain DGIN = 0 DGIN = 1		0.6438 1		V/V	
V <sub>IR</sub>	Analog input voltage range (Relative to VREF)  AX = 0 dB, attenuator on (DGIN = 0)  AX = 6.02 dB, attenuator on (DGIN = 0)  AX = 0 dB, attenuator off (DGIN = 1)  AX = 6.02 dB, attenuator off (DGIN = 1)		±1.584 ±0.792 ±1.02 ±0.51		Vpk	
V <sub>IOS</sub>	Offset voltage allowed on VIN	-50		50	mV	
Z <sub>IN</sub>	Analog input impedance to VREF, 300 to 3400 Hz	600		1400	kΩ	
I <sub>IP</sub>	Current into analog input for an input voltage of 3.3 V	50		115	_	2
I <sub>IN</sub>	Current out of analog input for an input voltage of -0.3 V	50		130	μΑ	2
Z <sub>OUT</sub>	VOUT output impedance		1	10	Ω	
CL <sub>OUT</sub>	Allowable capacitance, V <sub>OUT</sub> to AGND			500	pF	
I <sub>OUT</sub>	VOUT output current (F< 3400 Hz)	-4		4	mApk	3
V <sub>REF</sub>	VREF output open circuit voltage (leakage < 20 nA)	1.43	1.5	1.57	V	
Z <sub>REF</sub>	VREF output impedance (F < 3400 Hz)	70	110	130	kΩ	
V <sub>OR</sub>	VOUT voltage range(AR = 0 dB) (Relative to VREF)(AR = 6.02 dB)	7.0	±1.02 ±0.51		Vpk	
V <sub>OOS</sub>	VOUT offset voltage (AISN off)	-40		40		
V <sub>OOSA</sub>	VOUT offset voltage (AISN on)	-80		80	mV	4
G <sub>AISN</sub>	AISN gain - expected gain (input = 0 dBm0, 1014 Hz) Attenuator on (DGIN = 0) Attenuator off (DGIN = 1)	-0.016 -0.024		0.016 0.024	V/V	
PD	Power dissipation All channels active 1 channel active All channels inactive		130 40 13	170 80 18	mW	
CI	Digital Input capacitance			10	nE	
CO	Digital Output capacitance			10	pF	
PSRR	Power supply rejection ratio (1.02 kHz, 100 mV <sub>RMS</sub> , either path, GX = GR = 0 dB)	40			dB	

#### Notes:

- 1. The CD1, CD2, C3–C5 outputs are resistive for less than a 0.8 V drop. Total current must not exceed absolute maximum ratings.
- When the digitizer saturates, a resistor of 50 kΩ ±20 kΩ is connected either to AGND or to VCCA as appropriate to discharge the coupling capacitor.
- 3. When the QLSLAC device is in the Inactive state, the analog output will present either a VREF DC output level through a 15 k $\Omega$  resistor (VMODE = 0) or a high impedance (VMODE = 1).
- If there is an external DC path from VOUT to VIN with a gain of G<sub>DC</sub> and the AISN has a gain of h<sub>AISN</sub>, then the output offset will be multiplied by 1 / [1 − (h<sub>AISN</sub> G<sub>DC</sub>)].
- 5. Power dissipation in the Inactive state is measured with all digital inputs at VIH = VCCD and VIL = DGND and with no load connected to VOUT1, VOUT2, VOUT3, or VOUT4.

### **Transmission Characteristics**

Table 2. 0 dBm0 Voltage Definitions with Unity Gain in X, R, GX, GR, AX, and AR

Signal at Digital Interface	Transmit (DGIN = 0)	Transmit (DGIN = 1)	Receive	Unit
A-law digital mW or equivalent (0 dBm0)	0.7804	0.5024	0.5024	
μ-law digital mW or equivalent (0 dBm0)	0.7746	0.4987	0.4987	Vrms
±22,827 peak linear coded sine wave	0.7804	0.5024	0.5024	

When relative levels (dBm0) are used in any of the following transmission specifications, the specification holds for any setting of the GX gain from 0 dB to 12 dB, the GR loss from 0 dB to 12 dB, and the input attenuator (GIN) on or off.

Description		Test Conditions	Min	Тур	Max	Unit	Note
Gain accuracy, D/A or A/D		0 dBm0, 1014 Hz AX = AR = 0 dB 0 to 85° C -40° C	-0.25 -0.30		+0.25 +0.30		
		AX = +6.02 dB and/or AR = -6.02 dB 0 to 85° C -40° C	-0.30 -0.40		+0.30 +0.40	dB	
Gain accuracy digital-to-di	gital		-0.25		+0.25		
Gain accuracy analog-to-a	nalog		-0.25		+0.25		
Attenuation distortion		300 Hz to 3 kHz	-0.125		+0.125	1	1
Single frequency distortion	1				-46	1	2
Second harmonic distortio	n, D-A	GR = 0 dB			<del>-</del> 55		
Idle channel noise Analog out		Digital looped back weighted unweighted			-68 -55	dBm0p dBm0	3
Digital out		$\begin{array}{llllllllllllllllllllllllllllllllllll$		0	-78 12 -68 16	dBm0p dBrnc0 dBm0p dBrnc0	3 3, 6 3 3, 6
Crosstalk TX to same channel RX to		0 dBm0 300 to 3400 Hz 0 dBm0 300 to 3400 Hz			–75 –75	dBm0	
Crosstalk between channels TX or RX to TX TX or RX to RX		0 dBm0 SLIC imped. < 300 $\Omega$ 1014 Hz, Average 1014 Hz, Average			-76 -78	dBm0	4
End-to-end group delay		B = Z = 0; X = R = 1			678	μs	5

#### Notes:

- 1. See Figure 5 and Figure 6.
- 2. 0 dBm0 input signal, 300 Hz to 3400 Hz; measurement at any other frequency, 300 Hz to 3400 Hz.
- 3. No single frequency component in the range above 3800 Hz may exceed a level of -55 dBm0.
- 4. The weighted average of the crosstalk is defined by the following equation, where C(f) is the crosstalk in dB as a function of frequency,  $f_N = 3300 \text{ Hz}$ ,  $f_1 = 300 \text{ Hz}$ , and the frequency points  $(f_i, j = 2..N)$  are closely spaced:

$$\text{Average} = 20 \bullet log \boxed{ \frac{\displaystyle \sum_{j} \frac{10^{20}}{20} \bullet C(f_{j}) \frac{1}{20} \bullet C(f_{j-1})}{2} \bullet log \left(\frac{f_{j}}{f_{j-1}}\right)} \\ log \left(\frac{f_{N}}{f_{1}}\right)} }$$

- 5. The End-to-End Group Delay is the sum of the transmit and receive group delays (both measured using the same time and clock slot).
- 6. Typical values not tested in production.

### **Attenuation Distortion**

The signal attenuation in either path is nominally independent of the frequency. The deviations from nominal attenuation will stay within the limits shown in Figure 5 and Figure 6. The reference frequency is 1014 Hz and the signal level is -10 dBm0.

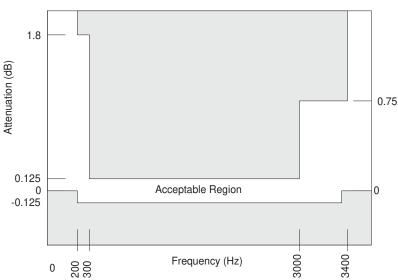
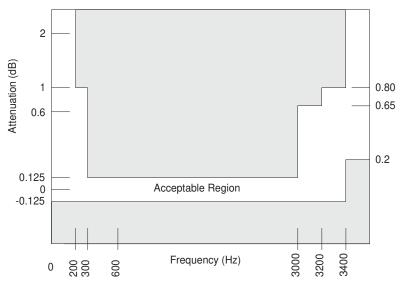


Figure 5. Transmit Path Attenuation vs. Frequency





## **Group Delay Distortion**

For either transmission path, the group delay distortion is within the limits shown in <u>Figure 7</u>. The minimum value of the group delay is taken as the reference. The signal level should be 0 dBm0.

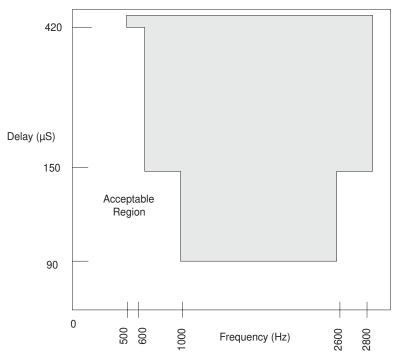


Figure 7. Group Delay Distortion

# **Gain Linearity**

The gain deviation relative to the gain at -10 dBm0 is within the limits shown in <u>Figure 8</u> (A-law) and <u>Figure 9</u> ( $\mu$ -law) for either transmission path when the input is a sine wave signal of 1014 Hz.

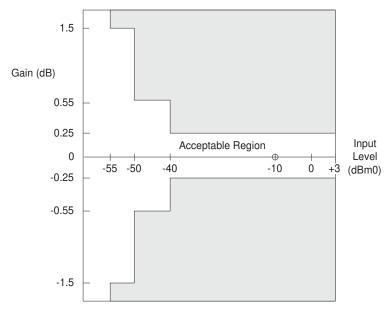
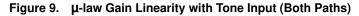
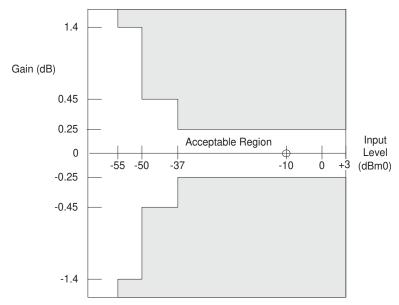


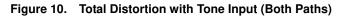
Figure 8. A-law Gain Linearity with Tone Input (Both Paths)

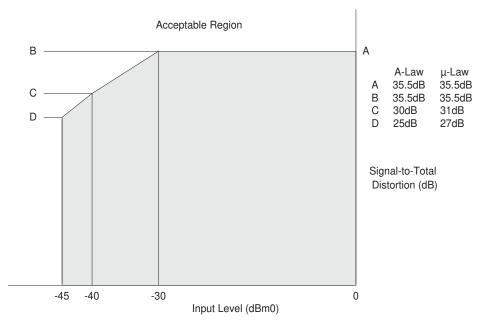




## **Total Distortion Including Quantizing Distortion**

The signal to total distortion ratio will exceed the limits shown in <u>Figure 10</u> for either path when the input signal is a sine wave signal of frequency 1014 Hz.





### **Discrimination Against Out-of-Band Input Signals**

When an out-of-band sine wave signal of frequency f, and level A is applied to the analog input, there may be frequency components below 4 kHz at the digital output which are caused by the out-of-band signal. These components are at least the specified dB level below the level of a signal at the same output originating from a 1014 Hz sine wave signal with a level of A dBm0 also applied to the analog input. The minimum specifications are shown in the following table.

Frequency of Out-of-Band Signal	Amplitude of Out-of-Band Signal	Level below A
16.6 Hz < f < 45 Hz	-25 dBm0 < A ≤ 0 dBm0	18 dB
45 Hz < f < 65 Hz	-25 dBm0 < A ≤ 0 dBm0	25 dB
65 Hz < f < 100 Hz	-25 dBm0 < A ≤ 0 dBm0	10 dB
3400 Hz < f < 4600 Hz	-25 dBm0 < A ≤ 0 dBm0	see Figure 11
4600 Hz < f < 100 kHz	-25 dBm0 < A ≤ 0 dBm0	32 dB

-10 -20 -28 dB -32 dB -30 -50 -50 -3.4 4.0 4.6 Frequency (kHz)

Figure 11. Discrimination Against Out-of-Band Signals

#### Note:

The attenuation of the waveform below amplitude A, between 3400 Hz and 4600 Hz, is given by the formula:

Attenuation (db) = 
$$14 - 14 \sin\left(\frac{\pi(4000 - f)}{1200}\right)$$

## Discrimination Against 12- and 16-kHz Metering Signals

If the QLSLAC device is used in a metering application where 12 kHz or 16 kHz tone bursts are injected onto the telephone line toward the subscriber, a portion of these tones also may appear at the VIN terminal. These out-of-band signals may cause frequency components to appear below 4 kHz at the digital output. For a 12 kHz or 16 kHz tone, the frequency components below 4 kHz are reduced from the input by at least 70 dB. The sum of the peak metering and signal voltages must be within the analog input voltage range.

## Spurious Out-of-Band Signals at the Analog Output

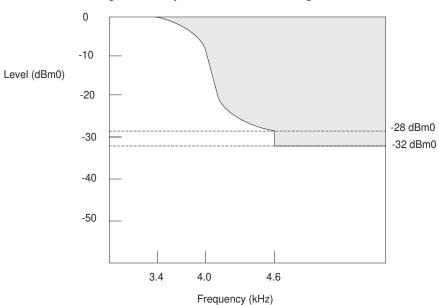
With PCM code words representing a sine wave signal in the range of 300 Hz to 3400 Hz at a level of 0 dBm0 applied to the digital input, the level of the spurious out-of-band signals at the analog output is less than the limits shown below.

Frequency	Level
4.6 kHz to 40 kHz	−32 dBm0
40 kHz to 240 kHz	-46 dBm0
240 kHz to 1 MHz	-36 dBm0

With code words representing any sine wave signal in the range 3.4 kHz to 4.0 kHz at a level of 0 dBm0 applied to the digital input, the level of the signals at the analog output are below the limits in <u>Figure 12</u>. The amplitude of the spurious out-of-band signals between 3400 Hz and 4600 Hz is given by the formula:

Level = 
$$\left[-14 - 14 \sin\left(\frac{\pi(f - 4000)}{1200}\right)\right] dBm0$$

Figure 12. Spurious Out-of-Band Signals

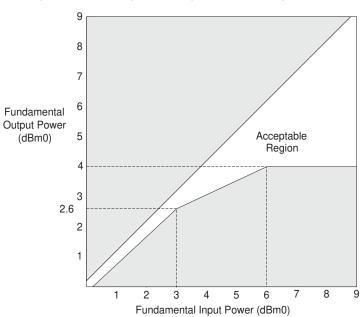


## **Overload Compression**

<u>Figure 13</u> shows the acceptable region of operation for input signal levels above the reference input power (0 dBm0). The conditions for this figure are:

- 1.  $1.2 \text{ dB} < GX \le + 12 \text{ dB}$
- 2.  $-12 dB \le GR < -1.2 dB$
- 3. Digital voice output connected to digital voice input.
- 4. Measurement analog-to-analog.

Figure 13. Analog-to-Analog Overload Compression



## **SWITCHING CHARACTERISTICS**

The following are the switching characteristics over operating range (unless otherwise noted). Min and max values are valid for all digital outputs with a 115 pF load, except CD1–C5 with a 30 pF load. (See Figure 15 and Figure 16 for the microprocessor interface timing diagrams.)

#### **Microprocessor Interface**

No.	Symbol	Parameter	Min	Тур	Max	Unit	Note
1	t <sub>DCY</sub>	Data clock period	122				
2	t <sub>DCH</sub>	Data clock HIGH pulse width	48				
3	t <sub>DCL</sub>	Data clock LOW pulse width	48				
4	t <sub>DCR</sub>	Rise time of clock			25		
5	t <sub>DCF</sub>	Fall time of clock			25		
6	t <sub>ICSS</sub>	Chip select setup time, Input mode	30		t <sub>DCY</sub> -10		
7	t <sub>ICSH</sub>	Chip select hold time, Input mode	0		t <sub>DCH</sub> -20		
8	t <sub>ICSL</sub>	Chip select pulse width, Input mode		8t <sub>DCY</sub>			
9	t <sub>ICSO</sub>	Chip select off time, Input mode	2500				1
10	t <sub>IDS</sub>	Input data setup time	25			200	
11	t <sub>IDH</sub>	Input data hold time	30			ns	
12	t <sub>OLH</sub>	SLIC device output latch valid			2500		
13	tocss	Chip select setup time, Output mode	30		t <sub>DCY</sub> -10		
14	tocsh	Chip select hold time, Output mode	0		t <sub>DCH</sub> -20		
15	tocsl	Chip select pulse width, Output mode		8t <sub>DCY</sub>			
16	tocso	Chip select off time, Output mode	2500				1
17	t <sub>ODD</sub>	Output data turn on delay			50		2
18	t <sub>ODH</sub>	Output data hold time	3				
19	t <sub>ODOF</sub>	Output data turn off delay			50		
20	t <sub>ODC</sub>	Output data valid			50		
21	t <sub>RST</sub>	Reset pulse width	50			μs	

#### **PCM** Interface

PCLK not to exceed 8.192 MHz.

Pull-up resistors to  $V_{CCD}$  of 240  $\Omega$  are attached to  $\overline{TSCA}$  and  $\overline{TSCB}$ . (See Figure 17 and Figure 18 for the PCM interface timing diagrams.)

No.	Symbol	Parameter	Min.	Тур	Max	Unit	Note
22	t <sub>PCY</sub>	PCM clock period	122				3
23	t <sub>PCH</sub>	PCM clock HIGH pulse width	48				
24	t <sub>PCL</sub>	PCM clock LOW pulse width	48				
25	t <sub>PCF</sub>	Fall time of clock			15		
26	t <sub>PCR</sub>	Rise time of clock			15		
27	t <sub>FSS</sub>	FS setup time	25		t <sub>PCY</sub> -30		
28	t <sub>FSH</sub>	FS hold time	50			ns	
30	t <sub>TSD</sub>	Delay to TSC valid	5		80	115	4
31	t <sub>TSO</sub>	Delay to TSC off	5		80		4, 5
32	t <sub>DXD</sub>	PCM data output delay	5		70		
33	t <sub>DXH</sub>	PCM data output hold time	5		70		
34	t <sub>DXZ</sub>	PCM data output delay to High-Z	5		70		
35	t <sub>DRS</sub>	PCM data input setup time	25				
36	t <sub>DRH</sub>	PCM data input hold time	5				

#### **Master Clock**

(See Figure 19, Master Clock Timing, on page 26.)

No.	Symbol	Parameter	Min	Тур	Max	Unit	Notes
37	J <sub>MCY</sub>	Master clock jitter			50		6
38	t <sub>MCR</sub>	Rise time of clock			15		
39	t <sub>MCF</sub>	Fall time of clock			15	ns	
40	t <sub>MCH</sub>	MCLK HIGH pulse width	48				
41	t <sub>MCL</sub>	MCLK LOW pulse width	48				

#### **Auxiliary Output Clocks**

No.	Symbol	Parameter	Min	Тур	Max	Unit	Notes
42	f <sub>CHP</sub>	Chopper clock frequency CHP = 0 CHP = 1		256 292.57		kHz	7
42A	DC <sub>CHP</sub>	Chopper click duty cycle		50		%	7
43	f <sub>E1</sub>	E1 output frequency (CMODE = EE1 = 1)		4.923		kHz	7
44	t <sub>E1</sub>	E1 pulse width (CMODE = EE1 = 1)		31.25		μs	7

#### Notes:

- 1. If CFAIL = 1 (Command 55h), GX, GR, Z, B1, X, R, and B2 coefficients must not be written or read without first deactivating all channels or switching them to default coefficients; otherwise, a chip select off time of 25 μs is required.
- 2. The first data bit is enabled on the falling edge of  $\overline{CS}$  or on the falling edge of DCLK, whichever occurs last.
- 3. The PCM clock frequency must be an integer multiple of the frame sync frequency. The maximum allowable PCM clock frequency is 8.192 MHz. The actual PCM clock rate is dependent on the number of channels allocated within a frame. The minimum clock frequency is 128 kHz in Companded state and 256 kHz in Linear state, PCM Signaling state, or double PCLK state. The minimum PCM clock rates should be doubled for parts with only one PCM highway in order to allow simultaneous access to all four channels.
- TSC is delayed from FS by a typical value of N t<sub>PCY</sub>, where N is the value stored in the time/clock-slot register.
- 5.  $t_{TSO}$  is defined as the time at which the output achieves the Open Circuit state.
- 6. PCLK and MCLK are required to be integer multiples of the frame sync (FS) frequency. Frame sync is expected to be an accurate 8 kHz pulse train. If PCLK or MCLK has jitter, care must be taken to ensure that all setup, hold, and pulse width requirements are met.
- 7. Phase jumps of 81 nS will be present when the master clock frequency is a multiple of 1.544 MHz.

## **SWITCHING WAVEFORMS**

Figure 14. Input and Output Waveforms for AC Tests

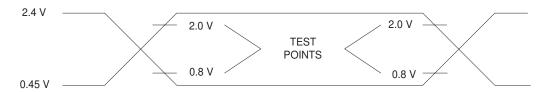


Figure 15. Microprocessor Interface (Input Mode)

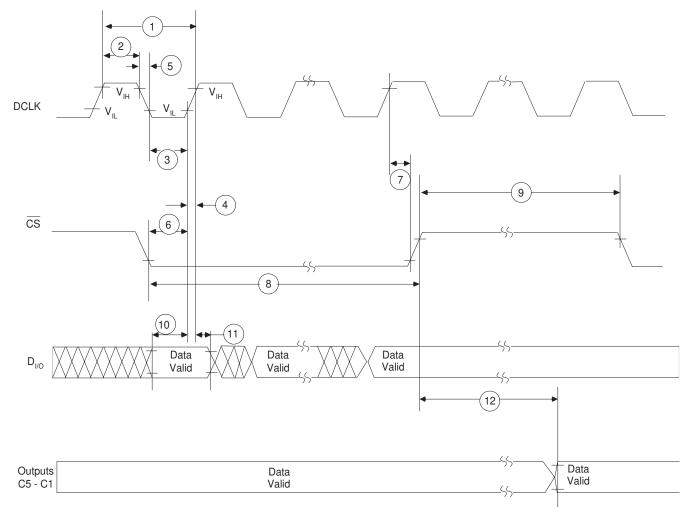


Figure 16. Microprocessor Interface (Output Mode)

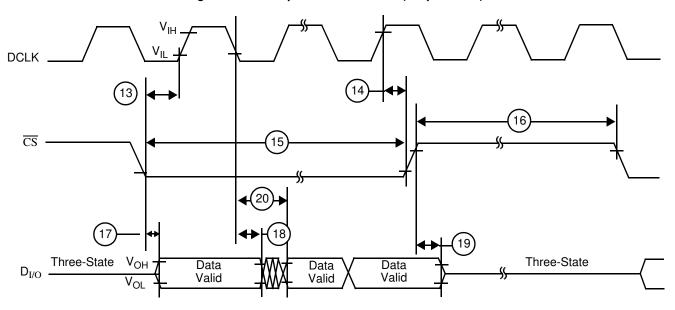


Figure 17. PCM Highway Timing for XE = 0 (Transmit on Negative PCLK Edge)

